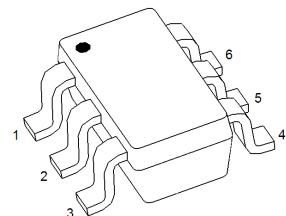


SL8820 Dual N-Channel MOSFET

$V_{(BR)DSS}$	$R_{DS(on)}\text{MAX}$	$I_D \text{ Max}$
20V	0.014 Ω @ 4.5V	6.0A
	0.018 Ω @ 2.5V	

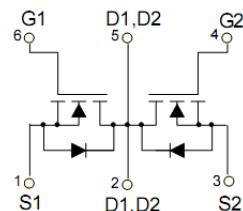
SOT-23-6



Equivalent Circuit

FEATURE

- TrenchFET Power MOSFET
- Excellent $R_{DS(on)}$
- Low Gate Charge
- High Power and Current Handing Capability
- Surface Mount Package



APPLICATION

- Battery Protection
- Load Switch
- Power Management

ABSOLUTE MAXIMUM RATINGS ($T_a=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	20	V
Gate-Source Voltage	V_{GS}	± 12	V
Continuous Drain Current	I_D	6	A
Pulsed Drain Current (note 1)	I_{DM}	25	A
Thermal Resistance from Junction to Ambient (note 2)	$R_{\theta JA}$	100	$^\circ\text{C}/\text{W}$
Junction Temperature	T_J	150	$^\circ\text{C}$
Storage Temperature	T_{STG}	-55~+150	$^\circ\text{C}$
Lead Temperature for Soldering Purposes(1/8" from case for 10 s)	T_L	260	$^\circ\text{C}$

MOSFET ELECTRICAL CHARACTERISTICS

T_a = 25 °C unless otherwise specified

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
STATIC CHARACTERISTICS						
Drain-source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250µA	20			V
Zero gate voltage drain current	I _{DSS}	V _{DS} = 19V, V _{GS} = 0V			100	nA
Gate-body leakage current	I _{GSS}	V _{GS} = ±12V, V _{DS} = 0V			±100	nA
Gate threshold voltage (note 3)	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250µA	0.5	0.7	1.0	V
Drain-source on-resistance (note 3)	R _{DS(on)}	V _{GS} = 4.5V, I _D = 6A	9.0	12.5	14	mΩ
		V _{GS} = 2.5V, I _D = 5.5A	12.0	15.5	18	mΩ
Forward transconductance (note 3)	g _F	V _{DS} = 5V, I _D = 6A		10		S
Diode forward voltage (note 3)	V _{SD}	I _S = 1.50A, V _{GS} = 0V			1.0	V
DYNAMIC CHARACTERISTICS (note 4)						
Input Capacitance	C _{iss}	V _{DS} = 10V, V _{GS} = 0V, f = 1MHz		615		pF
Output Capacitance	C _{oss}			150		pF
Reverse Transfer Capacitance	C _{rss}			120		pF
SWITCHING CHARACTERISTICS (note 4)						
Turn-on delay time	t _{d(on)}	V _{GS} = 5V, V _{DS} = 10V, R _L = 1.4Ω, R _{GEN} = 3Ω		7.2		ns
Turn-on rise time	t _r			13		ns
Turn-off delay time	t _{d(off)}			29		ns
Turn-off fall time	t _f			11		ns
Total Gate Charge	Q _g	V _{DS} = 10V, V _{GS} = 4.5V, I _D = 6A		12		nC
Gate-Source Charge	Q _{gs}			1.2		nC
Gate-Drain Charge	Q _{gd}			3.0		nC

Notes :

1. Repetitive rating: Pulse width limited by maximum junction temperature
2. Surface Mounted on FR4 board, t ≤ 10 sec.
3. Pulse test : Pulse width ≤ 300µs, duty cycle ≤ 2%.
4. Guaranteed by design, not subject to production.

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

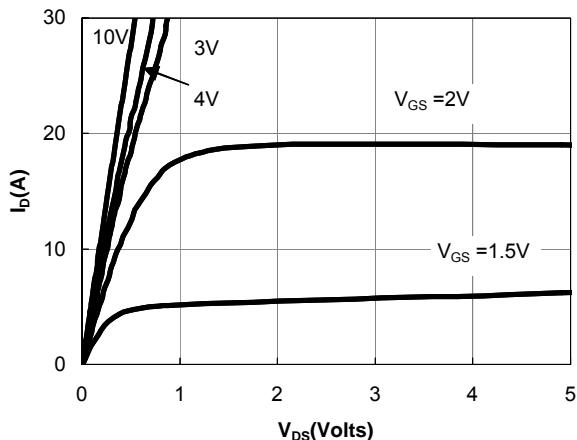


Figure 1: On-Regions Characteristics

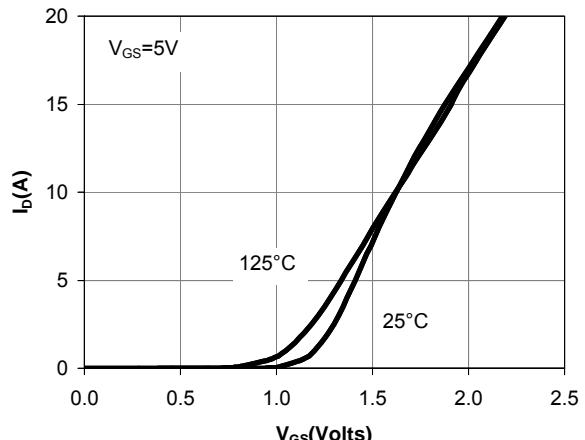


Figure 2: Transfer Characteristics

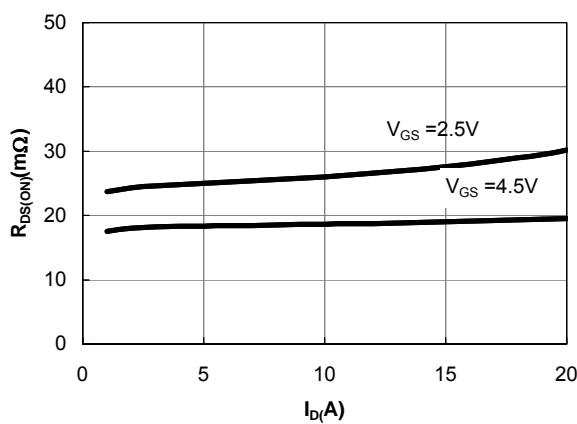


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

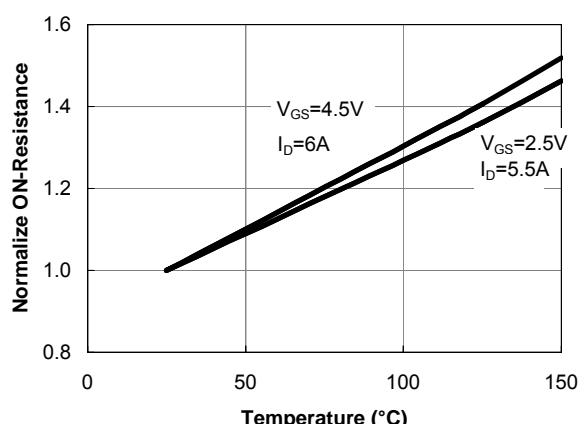


Figure 4: On-Resistance vs. Junction Temperature

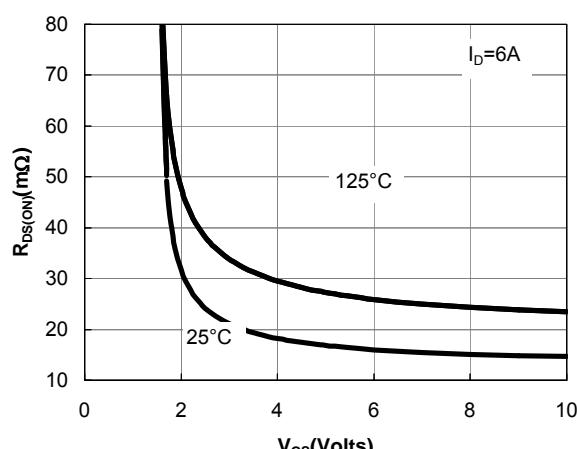


Figure 5: On-Resistance vs. Gate-Source Voltage

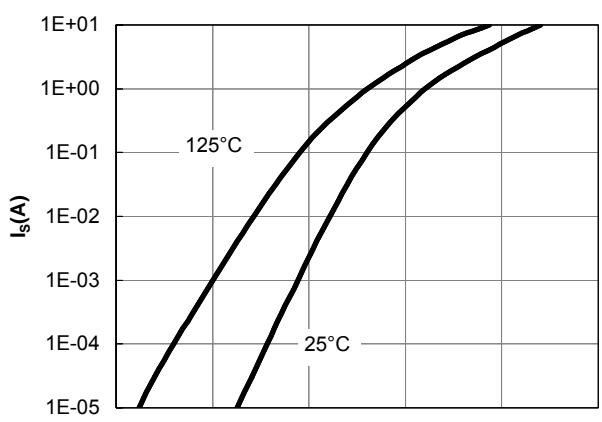
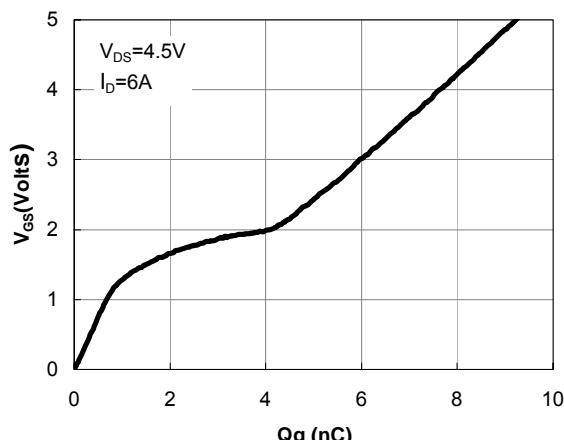
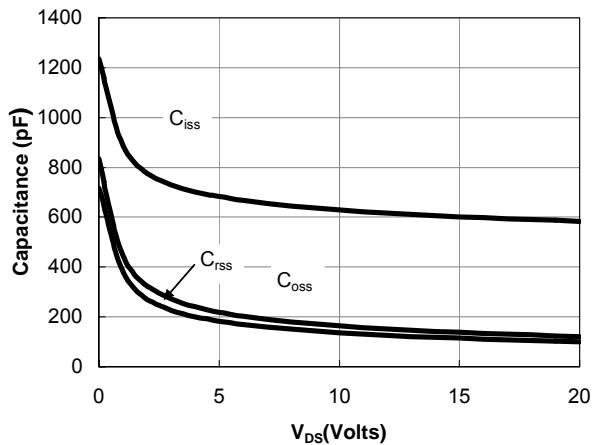
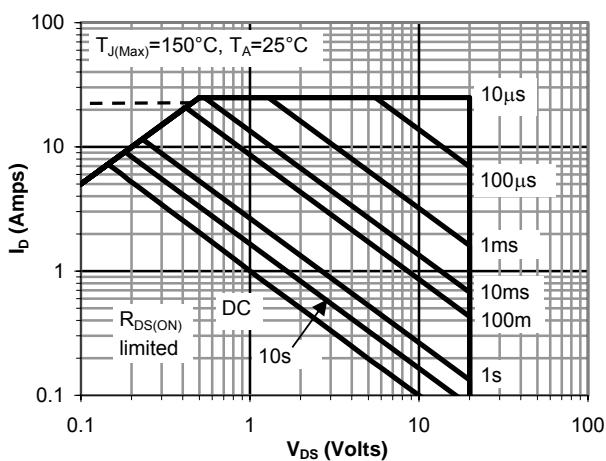
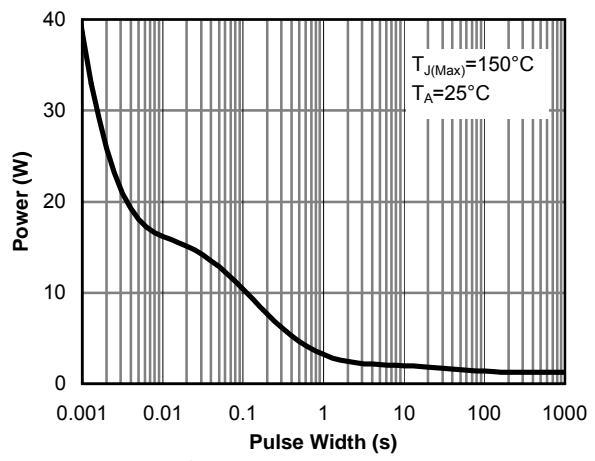
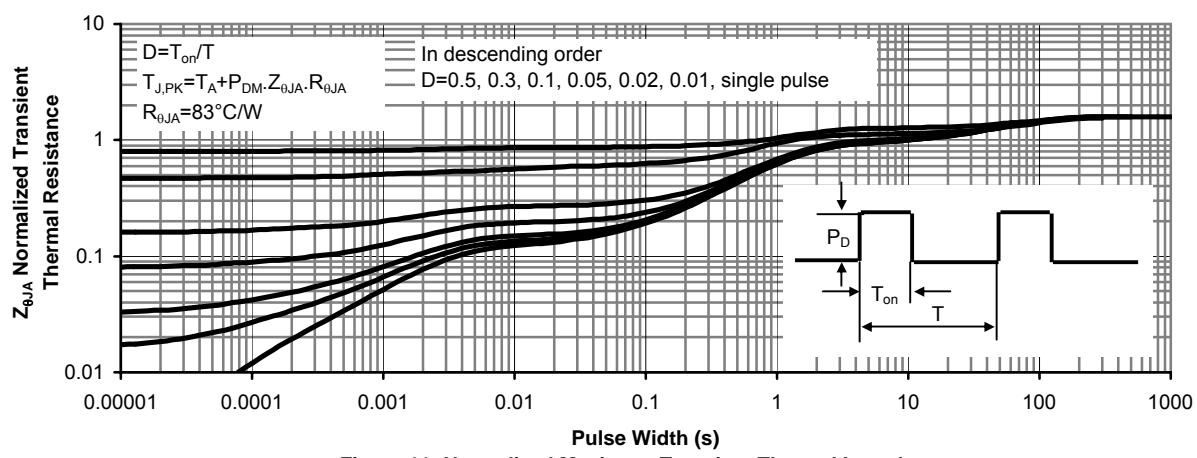
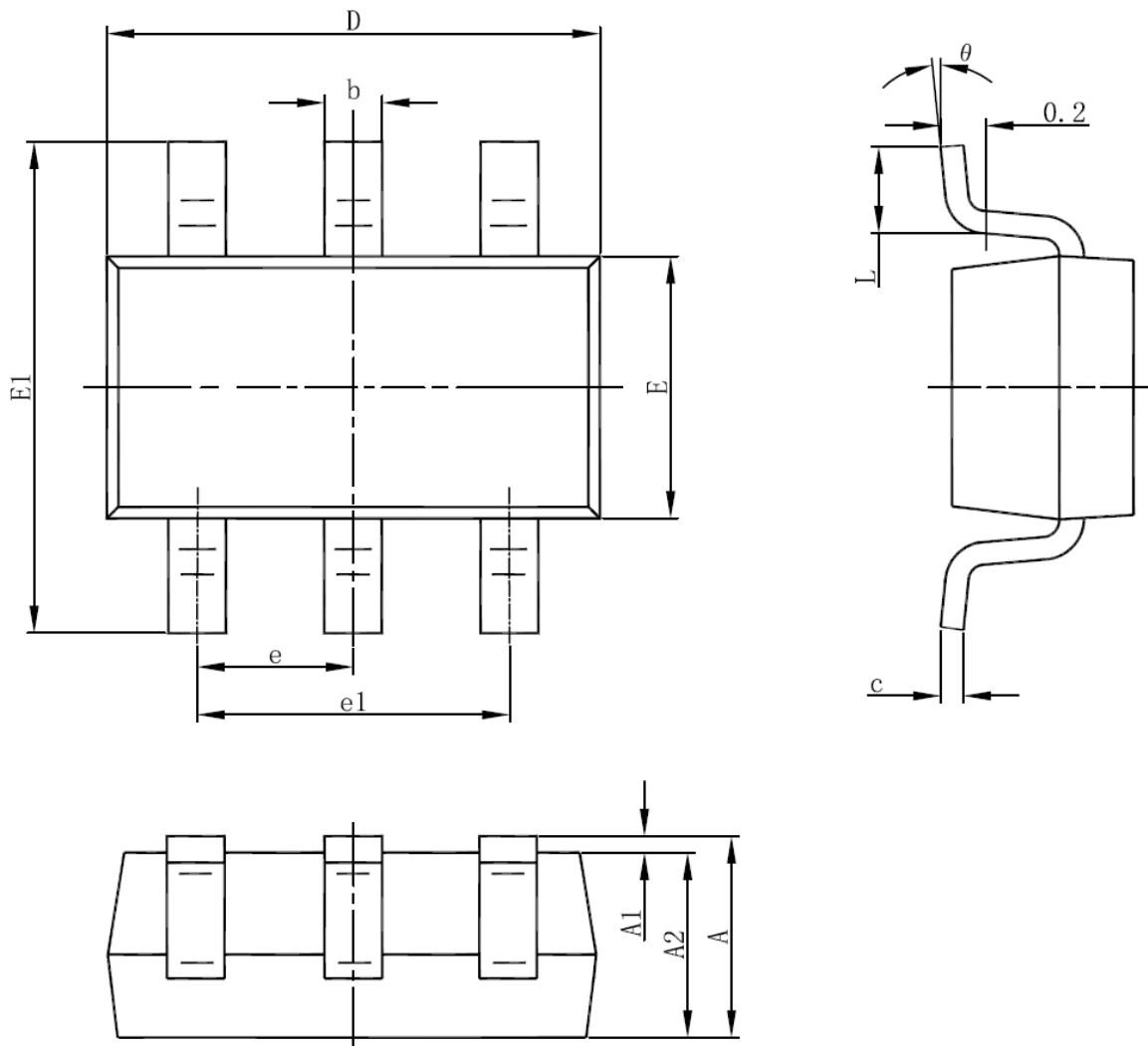


Figure 6: Body-Diode Characteristics

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS¹

Figure 7: Gate-Charge Characteristics

Figure 8: Capacitance Characteristics

Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

Figure 10: Single Pulse Power Rating Junction-to-Ambient

Figure 11: Normalized Maximum Transient Thermal Impedance

SOT23-6 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°